

# Understanding and Performing USB 2.0 Physical Layer Testing and Debugging

## Application Note

### Introduction

Engineers involved in the design, characterization and validation of USB 2.0 devices face daily pressures to speed new products to the marketplace. Tektronix comprehensive tool set enables designers to quickly and accurately perform electrical compliance tests recommended by the USB-Implementers Forum, Inc. (USBIF) and quickly debug their designs.

Universal Serial Bus (USB 2.0) is a connectivity specification aimed at peripherals that connect outside the computer in order to eliminate the hassle of opening the computer case to install cards needed for certain devices. USB-compliant devices translate into ease-of-use, expandability and speed for the user.

USB 2.0 device designers must properly characterize their designs and verify compliance to industry standards before device manufacturers can affix the “certified” USB-IF logo to their packaging. The appropriate tool set is critical for the performance of USB-IF compliance tests, such as eye diagram and parametric testing for low-speed, full-speed and high-speed devices and hubs.

Designs with USB 2.0 interfaces usually contain a variety of signals and buses. Tools that provide complete system visibility are needed to quickly verify and debug these designs. These tools need to quickly discover USB 2.0 problems and then they need to trigger on the problems to capture them. Next, the tools should easily search, mark and navigate long record lengths to find all problem occurrences. Finally, the tools should have automated USB 2.0 decode that provides insight to the design operation to quickly find the root cause of the problem.

The first part of this application note focuses on understanding and performing USB 2.0 physical layer measurements and electrical compliance testing (electrical and high-speed tests) and will include a discussion of the instruments required for each test. The last part of this application note focuses on debugging designs with USB 2.0 interfaces using a mixed signal oscilloscope with USB 2.0 triggering, searching and decoding capabilities.

## USB 2.0 Compliance Testing Basics

USB 2.0 is a serial bus that utilizes a 4-wire system —  $V_{BUS}$ , D-, D+ and Ground. D- and D+ are the prime carriers of the information.  $V_{BUS}$  supplies power to devices that derive their primary power from the host or hub.

USB 2.0 describes the following speed selections and rise times:

	Data Rates	Rise Times
Low Speed (LS)	1.5 Mb/s	75 ns – 300 ns
Full Speed (FS)	12 Mb/s	4 ns – 20 ns
High-Speed (HS)	480 Mb/s	100 ps

USB 2.0 devices can be either self-powered (having their own power supply) or bus-powered (drawing power through the host). It is imperative for the self-powered devices to draw as little power as possible. Tests are outlined in the USB 2.0 specifications for this aspect.

## USB 2.0 Electrical Tests

USB 2.0 electrical tests include signal quality, in-rush current check, and drop and droop tests.

### Signal Quality Test

Maintenance of signal quality is one of the keys to ensure that a USB 2.0 device is compliant and will be awarded the USB 2.0 certified logo.

The signal quality test includes:

- Eye Diagram testing
- Signal rate
- End of Packet (EOP) width
- Cross-over voltage range
- Paired JK Jitter
- Paired KJ Jitter
- Consecutive jitter
- Rise time
- Fall time

The eye diagram test is unique and the first of its kind for serial data applications.

The test set-ups for signal quality testing vary for upstream and downstream testing. In the case of upstream testing, signals transmitted from the device to the host are captured, whereas in the case of downstream testing, signals transmitted from the host are captured for testing. Downstream testing is usually performed on ports of a hub.

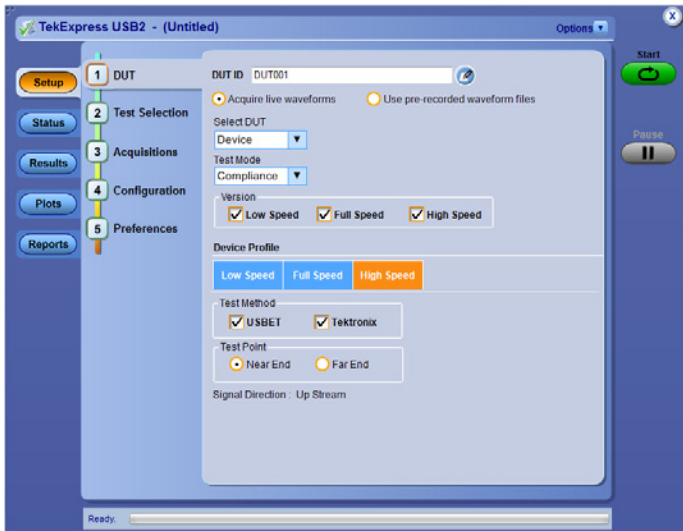


Figure 1. TekExpress USB2 compliance test package running on a DPO7254C.



Figure 2. Measurement results are automatically displayed using the TekExpress USB2 compliance test package.

While performing compliance testing, you need to set up the worst-case USB 2.0 topology scenario to ensure a sufficient test margin. Devices are tested in the 6th tier to ensure the worst-case scenario. Further, each hub level is referred to as a tier. The hub-under-test (HUT) is plugged into the 5th tier so that it operates on the 6th tier.

### Test Equipment

Signal quality testing requires a real-time oscilloscope with a bandwidth of 2 GHz or higher, such as the MSO/DPO5204B, DPO7254C or DPO7354C, for high speed USB signals, and an oscilloscope with a bandwidth of 350 MHz or higher, such as any of the MSO/DPO5000 or DPO7000C Series, for low and full speed USB signals. Single-ended probes like the TAP1500, TAP2500, TAP3500, and P6245<sup>†1</sup> are needed for low and full speed USB testing. Differential probes such as the TDP1500, TDP3500, and P6248<sup>†1</sup> are required for high speed USB testing. In addition, this testing requires test software and the USB2SIGQUAL test fixture from USB-IF.

Figure 1 shows the operation of the TekExpress USB2 (option USB2) compliance test package and the high-speed signal

quality test fixture on a DPO7254C. This test package fully automates the signal quality test process, allowing designers to perform quick and easy tests on their designs. Note, the TekExpress USB2 integrates and automates the USB-IF USBET Electrical Analysis software thereby ensuring you get the exact results as if you had run USBET software separately.

A user must select the measurements to be performed for a particular signal speed (low, full or high speed). The application must then be configured based on tier (tier to which the DUT is connected), test point (test point of the DUT — near or far end), and direction of traffic (upstream or downstream testing), as shown in Figure 1. After completing these two steps, the user then runs the application. For high speed testing, tier selection is not applicable and near end is the standard test point.

The test package eliminates the task of manual, time-consuming oscilloscope set-ups, cursor placements and comparison of test results with USB 2.0 specifications. The results are automatically displayed as a results summary and details, as illustrated in Figure 2.

<sup>†1</sup> Requires a TPA-BNC adapter when used on an MSO/DPO5000 or DPO7000C Series model.

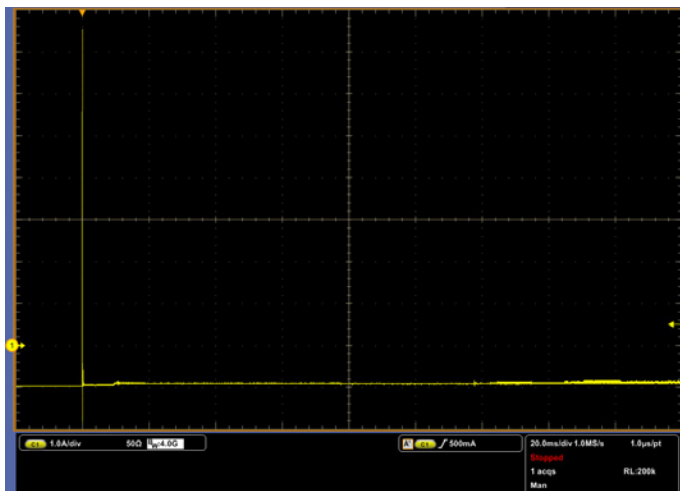


Figure 3. Illustration of a sharp intake of current.

### In-Rush Current Check

Because USB 2.0 is a hot-pluggable technology, extreme care is required to ensure that the current drawn by a device does not exceed a specified limit. If the current drawn exceeds a specified value, the operation of other USB 2.0 devices connected to the bus may be hampered. The in-rush current check is performed for both self-powered and bus-powered devices to verify that the device-under-test (DUT) does not draw too much current when plugged into the port of a hub.

Typically, one expects a sharp intake of current when a device is plugged in. One may observe small humps or perturbations in the current trace depending on when the device is reset.

Theoretically, an in-rush current check involves the calculation of the integral of current over a certain period of time (bounded by the location of two vertical cursors on the oscilloscope).

The USB 2.0 specification dictates that the total charge drawn by the device should be less than or equal to 51.5 uC for a  $V_{BUS}$  value of 5.15 V. (The waiver limit for this test is less than 150 uC).

### Test Equipment

The in-rush current check requires a real-time oscilloscope, and current probes, like the TCP0030A. This test also requires

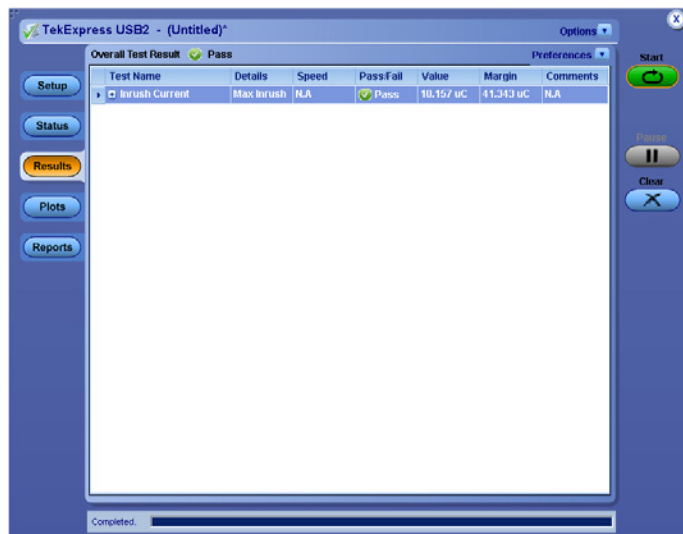


Figure 4. Inrush test results shown in TekExpress USB2.

test software and a test fixture, such as the option USB2 compliance test package. The TekExpress USB2 test package can be used to automatically set up the oscilloscope for the in-rush current check. This test package provides direct readout of Charge (uC), Capacitance (uF) and an automatic indication of pass or fail.

### Drop Test

The USB 2.0 specification requires powered USB ports to provide a  $V_{BUS}$  between 4.75 and 5.25 V while bus-powered hubs maintain a  $V_{BUS}$  at 4.4 V or greater. Drop testing evaluates  $V_{BUS}$  under both no-load and full-load (100 mA or 500 mA, as appropriate) conditions.

$$V_{drop} = V_{upstream} - V_{downstream}$$

$$V_{upstream} = V_{BUS} \text{ at the hub's upstream connection}$$

$$V_{downstream} = V_{BUS} \text{ at one of the hub's downstream ports}$$

Bus-powered hubs must have a  $V_{drop} \leq 100$  mV between their downstream and upstream ports when 100 mA loads are present on their downstream ports. This requirement ensures that the hubs will supply 4.4 V to a downstream device. Bus-powered devices with Captive cables must have  $V_{drop} \leq 350$  mV between the upstream connector and downstream port, including the drop through the cable.

## Test Equipment

Drop tests require a multi-meter. The Keithley multi-meters provide adequate readout to ensure accurate results of the Drop tests.

## Droop Test

Vdroop equals the difference in  $V_{BUS}$  voltage when a no-load condition is applied and when a 100 mA load is applied to the port-under-test (PUT) (all other ports are fully loaded). The USB 2.0 specification allows a maximum droop of 330 mV. The droop test evaluates worst-case droop by alternately applying a 100 mA load and no-load condition to the port under test while all other ports are supplying the maximum load possible. All  $V_{BUS}$  measurements are relative to local ground.

## Test Equipment

Droop tests require a real-time oscilloscope, such as a DPO7254C, and single-ended probes, like the TAP1500, P6243<sup>2</sup> or P6245<sup>2</sup>. In addition, this testing requires test software and a test fixture, such as the option USB2 compliance test package.

The test package automatically sets up the oscilloscope for the desired test configuration. Running the application acquires the signal, provides the  $V_{droop}$  measurement, and subsequently provides a pass or fail indication and detailed measurement results of the test.

## USB 2.0 High-speed Tests

Fundamentally, USB 2.0 device compliance tests closely follow the compliance test protocol for USB 1.1 devices. Primary additions concern USB 2.0 high-speed mode. High-speed mode adds a new level of complexity to USB device design. USB 2.0 high-speed tests include receiver sensitivity, CHIRP, monotonicity and impedance measurement tests.

## Receiver Sensitivity Test

To increase robust operation in a noisy environment, a USB 2.0 high-speed device (or downstream port) must respond to IN<sup>2b</sup> tokens with NAKs<sup>2b</sup> when the signal level equals or exceeds the specified level. The test requires placement of the DUT in Test\_SE0\_NAK mode. The host is then replaced by the signal from a signal generator to continue to transmit IN tokens. The signal amplitude is presented to the DUT at a level at or above 150 mV. At these levels, the DUT must be in the unsquelched mode, responding to IN packets with NAKs. The amplitude is then reduced to <100 mV and at this level, the DUT must be squelched and does not respond to IN tokens with NAKs.

<sup>2</sup> Requires a TPA-BNC adapter when used on an MSO/DPO5000 or DPO7000 Series model.

<sup>2b</sup> Please refer to the USB 2.0 specifications for more information about IN tokens and NAKs.

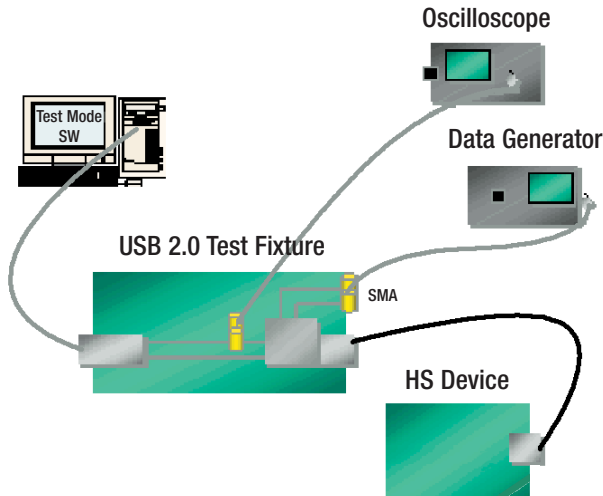


Figure 5. Set-up for a receiver sensitivity test using a DPO7254C and a Tektronix signal source.

## Test Equipment

The receiver sensitivity test requires a real-time oscilloscope, such as a MSO/DPO5204B or DPO7254C or higher bandwidth model, and a high speed data source that can transmit IN tokens of varying amplitude, such as a Tektronix AWG5000C or AWG7000C Series Arbitrary Waveform Generator. This test also requires differential probes, like a TDP1500, TDP3500, or P6248<sup>3</sup>, and test software and the TDSUSBF test fixture.

Figure 5 shows the set-up to perform this test using an oscilloscope and data generator. The option USB2 test package provides automated set-ups and the test patterns for the signal source, needed for receiver sensitivity testing.

## CHIRP Test

The CHIRP test examines the basic timing and voltages of both upstream and downstream ports during the speed detection protocol. For a hub, the CHIRP test must be performed on both upstream and downstream ports.

To perform CHIRP testing, the DUT is hot-plugged and signaling is measured with single-ended probes on both data lines. Data is analyzed for CHIRP K amplitude, CHIRP K duration, Reset duration, Number of KJ pairs before High Speed termination and delay after KJKJKJ before device-applied termination.

<sup>3</sup> Requires a TPA-BNC adapter when used on an MSO/DPO5000 or DPO7000 Series model.

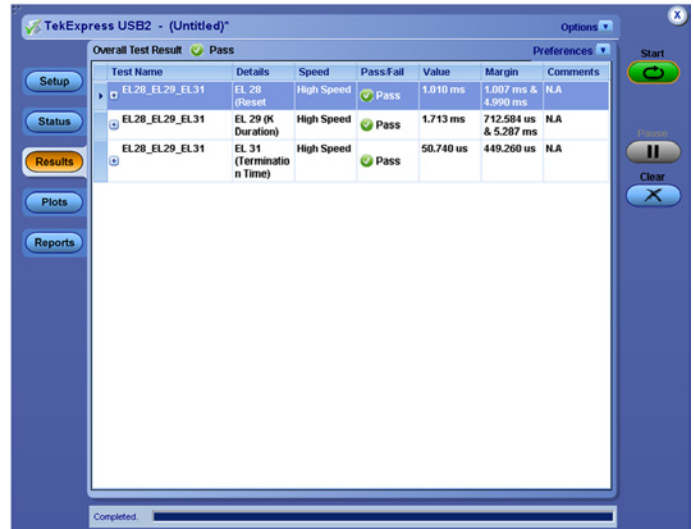
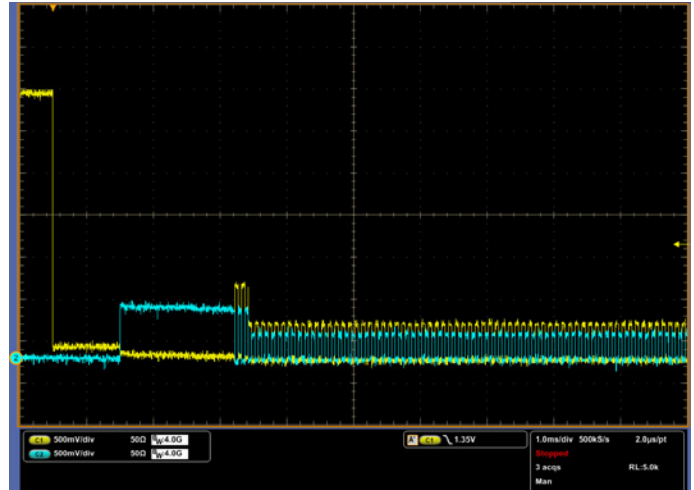


Figure 6. Test parameters for a CHIRP test.

Figure 6 illustrates the CHIRP test.

## Test Equipment

The CHIRP test requires a 2 GHz or higher bandwidth real time oscilloscope, such as a MSO/DPO5204B or DPO7254C, with single-ended probes, like a TAP1500, TAP2500, TAP3500, P6243<sup>3</sup> or P6245<sup>3</sup>. In addition, this test requires test software and the TDSUSBF test fixture, such as the option USB2 compliance test package.

Manual analysis of the various CHIRP types and conditions is a time-consuming process. The test package automates this process and automatically documents the results.

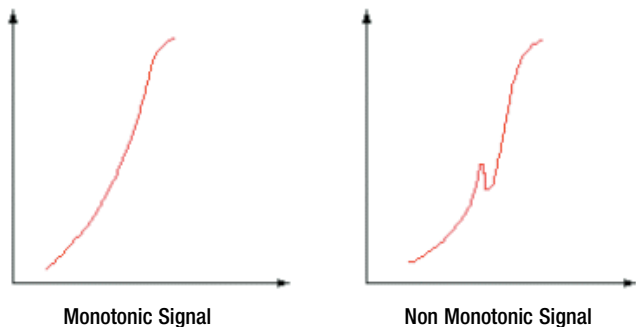


Figure 7. Illustration of monotonic and non-monotonic USB 2.0 high-speed signals with a rise time of 500 ps.

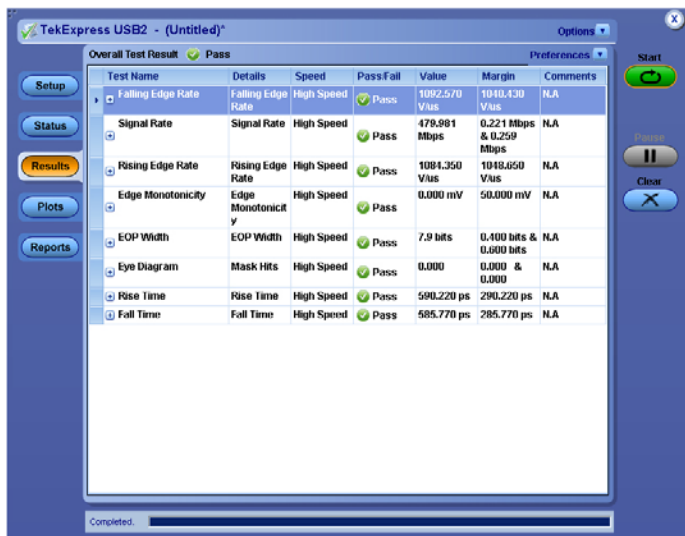


Figure 8. The TekExpress USB2 compliance test package captures the test packet and examines each rising and falling edge for monotonic operation.

### Monotonicity Test

When performing a USB 2.0 high-speed compliance test, a developer needs to verify that the signal under question is monotonic. Monotonicity verifies that a transmitted signal should smoothly increase or decrease in amplitude without deviation in the opposite direction. Non-monotonic signal behavior is caused by metastability, high-frequency noise and jitter problems in a circuit. Figure 7 compares a monotonic signal with a non-monotonic signal using a USB 2.0 high-speed signal with a rise time of 500 ps.

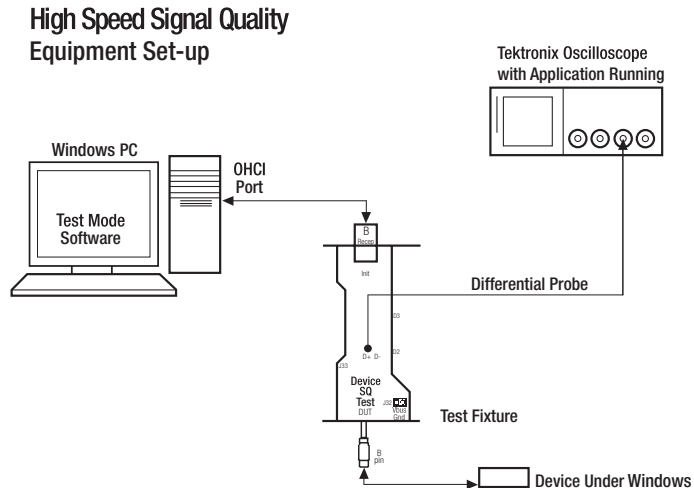


Figure 9. The monotonicity test set-up uses the high-speed signal quality test configuration.

### Test Equipment

To verify monotonic behavior of a signal, the oscilloscope used should have a sample rate high enough to capture as many sample points as possible on a rising or falling edge. In addition, the oscilloscope should have enough bandwidth to ensure that the high frequency non-monotonic transition is not attenuated. Hence, an oscilloscope with a sample rate of 10 GS/s and a bandwidth of 2 GHz or higher, such as the MSO/DPO5204B, DPO7254C or DPO7354C, is the ideal tool for monotonicity testing.

The monotonicity test for a USB 2.0 device is verified during test packet examination. The option USB2 compliance test package captures the test packet and examines each rising and falling edge for monotonic behavior, as shown in Figure 8. Set-up uses the high-speed signal quality test configuration, as illustrated in Figure 9. The TekExpress USB2 compliance test package, coupled with a high-performance oscilloscope, automates this process and ensures repeatability of test results.

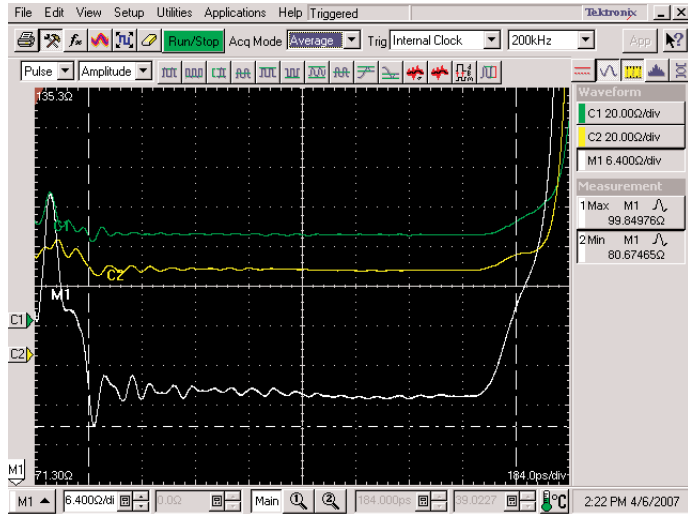


Figure 10. TDR measurement made with a DSA8300 sampling oscilloscope coupled with an 80E04 TDR sampling module.

### Impedance Measurement Test

Due to the high signal rates of USB 2.0 High-Speed mode, trace and packaging impedance have become critical parameters. The USB 2.0 High-Speed specification requires differential impedance measurements of cables, silicon and devices.

The USB 2.0 specification requires that the differential TDR impedance step response be set to 400 ps. The USB specification defines the impedance limits referenced from the DUT connector. In general, the impedance should be between 70 Ohm and 110 Ohm at a given distance from the connector. Cables are also required to meet specific impedance limits. These limits are 90 Ohm +/- 15%.

### Test Equipment

The impedance measurement test requires a time domain reflecto-meter, such as the DSA8300 digital serial analyzer sampling oscilloscope with 80E04 TDR sampling module, which offers unmatched TDR performance on up to eight channels simultaneously. Add the IConnect product to convert from TDR measurements to S-parameters.

Figure 10 shows a TDR measurement made with the DSA8300 sampling oscilloscope. The Min and Max measure within the tolerance specified by the USB differential specification of 90 Ohm +/- 15%.

Test Equipment	Signal Quality Test	Inrush Current Check	Drop Test	Receiver Sensitivity Test	CHIRP Test	Impedance Measurement Test
Real-time Oscilloscope	Y	Y	Y	Y	Y	
Time Domain Reflectometer						Y
Signal Generator				Y		
Test Fixture	Y	Y	Y	Y	Y	Y
Test Software	Y	Y	Y	Y	Y	
Differential Probes	Y			Y		
Single-ended Probes	Y		Y		Y	
Current Probes		Y				

### Instrumentation Requirements for USB 2.0 Physical Layer Testing

USB 2.0 opens up a whole range of USB consumer applications to make the PC a more user friendly and valuable tool in the workplace and home. With any consumer product opportunity, time to market is crucial. USB designers are keenly aware that the correct tool aids in meeting schedule objectives. Especially critical are the bandwidth, rise time and sample rate of the oscilloscope, along with the test fixture and fully automatic test software.

USB 2.0 physical layer validation and electrical compliance testing require a host of test equipment, as the chart above illustrates.



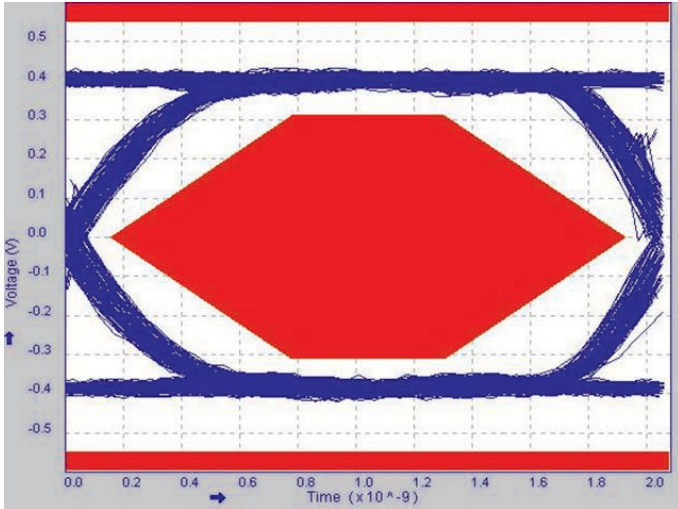


Figure 11. DPO7254C digital phosphor oscilloscope.

## Selecting Tools for USB 2.0 Physical Layer Testing

### Real-Time Oscilloscope

A real-time oscilloscope is the most crucial test instrument for USB 2.0 measurements. When selecting an oscilloscope for these measurements, it is important to consider the oscilloscope's rise time, bandwidth and sample rate. The following section deals with the required performance characteristics of the real-time oscilloscope.

### Effect of Oscilloscope Bandwidth/Rise Time on Measurement Accuracy

Rise time needs of the oscilloscope depend closely on the rise times or slew rate of the signals to be measured. The following empirical formula gives the relation between measured rise time [RT(measured)], oscilloscope rise time [RT(oscilloscope)] and signal rise time [RT(signal)];

$$RT(\text{measured}) = \sqrt{[RT(\text{signal})]^2 + RT(\text{oscilloscope})^2}$$

Typical edge rates of USB 2.0 silicon are in the 300-500ps range and an oscilloscope with rise time performance faster than this is recommended. However, slower oscilloscope rise times would signify higher error in measurements with respect to signals. Therefore, in order to measure a signal with a rise time of a typical USB 2.0 signal with less than 10-15% error, the oscilloscope used should ideally have a rise time of 100-180 ps, like a DPO7254C.

## Effect of Oscilloscope Sample Rate on Testing

To capture information at edge speeds as fast as 500 ps, you need at least 10 sample points on an edge. This requirement becomes even more important when performing a monotonicity test, mandatory for high-speed testing.

### Tektronix Solutions

The following chart lists various Tektronix real-time oscilloscopes.

Specification	DP07254C	DP07354C	DP070404C
Rise/Fall Time	160 ps	115 ps	98 ps
Sample Rate (1 ch)	40 GS/s	40 GS/s	25 GS/s

Note: USB 2.0 can encounter edge rates as fast as 100 ps.

The DPO7254C digital phosphor oscilloscope is just one of the high performance members of the Tektronix's Windows-based oscilloscopes. With 40 GS/s maximum real-time sample rate and 2.5 GHz bandwidth, the four-channel DPO7254C strikes a balance between high performance and affordability for verification, debug and characterization of USB 2.0 designs. This instrument features exceptional signal acquisition performance, operational simplicity and open connectivity to the design environment. The DPO7254C delivers more than 250,000 wfms/s waveform capture rate, enabled by proprietary DPX® acquisition technology, to detect and capture elusive events with confidence and ease.

Other higher bandwidth oscilloscopes from Tektronix can also be used within the probes, software, and accessories mentioned here to perform USB compliance tests.

### Time Domain Reflectometer

A time domain reflectometer is required for the impedance measurement test. The DSA8300 digital sampling oscilloscope with 80E04 TDR sampling module provides true differential time domain reflectometry (TDR), making it an ideal solution for USB 2.0 device and cable impedance measurements. This oscilloscope and sampling module can display both the individual positive and negative TDR waveforms of differential line characteristics and directly measure the impedance of each conductor or common mode voltage of the differential line. This test system can also display the true differential measurements of both these lines and display the impedance in the unit of ohms, providing the user with the required measurements to validate any USB 2.0 device.

### Signal Source

A signal source is required for the receiver sensitivity test. The Tektronix AWG5000C and AWG7000C Series are excellent signal sources for USB receiver sensitivity tests.

Setup files to perform USB 2.0 receiver sensitivity tests for all of these signal sources are provided by Tektronix.

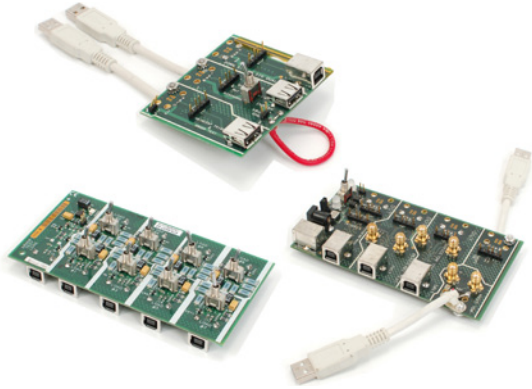


Figure 12. TDSUSBF Test fixture.

## Test Fixture

The test fixture is the most crucial component that enables probing for every test set-up. The ideal test fixture should provide access to the differential data lines (D+, D-) and  $V_{BUS}$  and offer access/connections via on-board USB connectors or wired dongles.

For receiver sensitivity testing, SMA cables are needed to connect the data generator to data lines to stimulate the device. Cable access is also needed to allow impedance measurements by a TDR measurement device.

The TDSUSBF is a comprehensive compliance test fixture to enable USB 2.0 testing, as shown in Figure 12. Additionally, for high-speed Signal Quality measurements the USBSIGQUAL fixture set is required for Host and Device testing, as shown in Figure 13. This fixture set is provided by USB-IF.



Figure 13. USB2SIGQUAL Host and Device fixture set.

## Test Software

A user may choose among fully automatic test software, semi-automated test software and manual testing.

### Fully Automatic Test Software

Fully automatic test software, such as the option USB2 compliance test package, substantially improves test efficiency by providing automatic oscilloscope set-ups, automated highspeed tests and quick “one-touch” testing. This test package drastically reduces the test time and chances of any erroneous measurements.

## Probes

Probes are a critical component of the measurement system to perform various USB 2.0 compliance tests. Tektronix offers differential (P6248<sup>4</sup>, TDP1500, TDP3500), single-ended (P6245<sup>4</sup>, TAP1500, TAP2500, TAP3500) and current (TCP202A<sup>4</sup>, TCP0030A) probes that allow access to high-density boards with fine-pitch, hard-to-reach components while maintaining maximum signal fidelity.

<sup>4</sup> Requires a TPA-BNC adapter when used on an MSO/DPO5000 or DPO7000 Series model.

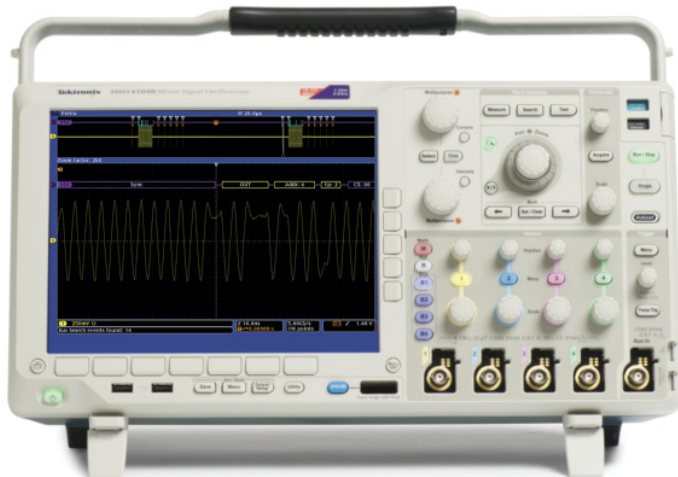


Figure 14. MSO4104B oscilloscope with four analog channels and 16 digital channels with digital per-channel threshold settings.

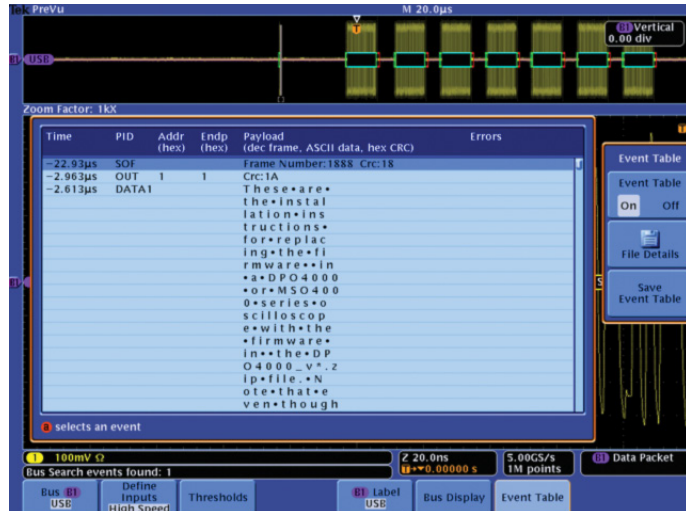


Figure 15. MSO4104B Event Table display of high-speed USB data, triggered on the text string “zip”.

## Debugging USB 2.0 Designs

Product designs with USB 2.0 interfaces usually contain a wide variety of analog and digital signals, as well as parallel and serial buses. For example, I2C and SPI buses are commonly used for inter-integrated circuit communications in embedded systems. For quick verification and debugging, a time-correlated view of all these mixed signals and buses is required.

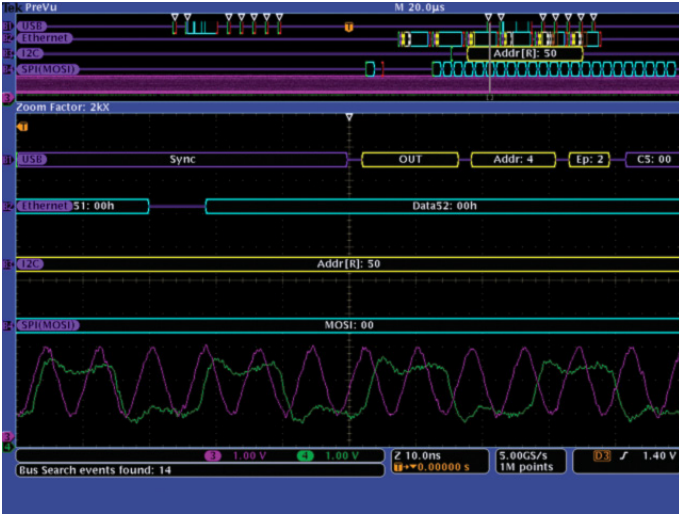
### Test Equipment

The MDO3000, MDO/MSO/DPO4000B, MSO/DPO5000B, DPO7000C, and MSO/DSA/DPO70000C Series oscilloscopes provide the feature-rich tools you need to speed the debugging of your USB 2.0 designs. All models provide four analog channels and optional USB 2.0 triggering and analysis. The MDO3000, MDO/MSO4000B, MSO5000B, and MSO70000C series Mixed Signal Oscilloscopes also provide 16 digital channels and parallel bus triggering and

analysis. See Figure 14.

These oscilloscopes, with the TDP1000 1 GHz Differential Probe and the USB triggering and analysis application, can trigger, decode, and search on USB 2.0 low-speed, full-speed and high-speed buses. The oscilloscope's serial trigger can isolate and capture a wide range of USB 2.0 packet content, protocol errors and data values.

In Figure 15, the oscilloscope has triggered on the ASCII text string “zip” on the USB 2.0 high-speed bus. The decoded bus is displayed in an Event Table format and the table can be saved for documentation and for analysis with other software tools.



**Figure 16.** Acquisition showing USB 2.0 high-speed decode, Ethernet 100BASE-TX with TCP/IPv4 protocol decode, I2C decode, SPI decode and two analog signals.



**Figure 17.** Simplified display, showing only the differential high-speed USB analog signal and the decoded bus.

### Time-Correlated Bus Decode

Time-correlated displays of complex system interactions are critical to efficient embedded system debug, including combinations of analog and digital signals, parallel buses, and serial buses. The MSO/DSA/DPO70000C, DPO7000C, and MSO/DPO5000 Series oscilloscopes with the SR-USB application software can decode and display up to 16 buses at a time, while the MDO/MSO/DPO4000B Series oscilloscope with the DPO4USB application module can decode and display up to 4 buses and the MDO3000 Series oscilloscope with the MDO3USB application module can decode and display up to 2 buses. The buses are displayed in color-coded bus forms that are time correlated with the analog and digital signals. Figure 16 shows an acquisition with USB 2.0 high-speed decode, Ethernet 100BASE-TX with TCP/IPv4 decode, I<sup>2</sup>C decode, SPI decode, and two analog signals which are all time-correlated. This single display provides in-depth insight to the operation of this design.

### Wave Inspector Navigation and Advanced Search and Mark

The deep record lengths of these oscilloscopes represent thousands of full-resolution screens of data. Even with manually scrolling through the waveforms at the rate of one screen (1,000 points/screen) per second, you could spend hours looking at a single acquisition. The front panel Wave Inspector controls on the MSO/DPO5000, MDO/MSO/DPO4000B and MDO3000 Series provide manual navigation tools and automated searches (including searches on serial buses) that simplify the task of working with large acquisitions. The MSO/DSA/DPO70000C, DPO7000C, and MSO/DPO5000 Series offer Advanced Search and Mark which enables up to 8 simultaneous automatic search functions.

In Figures 16 and 17, the automated bus search finds 14 occurrences of a USB 2.0 Sync field. These events are marked with white hollow triangles above the waveforms. Now that the USB 2.0 Syncs have been marked, navigating to the beginning of each USB 2.0 packet is as simple as pressing the front-panel Previous and Next arrow buttons. Also, you can press the Set/Clear front-panel button to mark the acquisition at other places of interest so that you can quickly return to them for further analysis.

## Conclusion

USB 2.0 technology provides the device designer a migration path for high-performance peripherals that preserve the ease-of-use consumers have come to demand. However, this tremendous increase compatibility also presents new design challenges that the device designer must resolve.

Tektronix offers a comprehensive tool set — sophisticated mixed-signal oscilloscopes, true differential TDR, high-speed signal generators, industry-leading probes, USB 2.0 triggering and analysis applications, and a fully automated compliance test package — to enable USB 2.0 device designers to perform quick and accurate electrical compliance testing and physical layer validation of their designs. Collectively, this tool set provides superior performance with unparalleled ease-of-use, making it an ideal solution for USB 2.0 measurements.

Tektronix maintains a complete library of updated resources for the USB device designer at [www.tektronix.com/usb](http://www.tektronix.com/usb).

### Contact Tektronix:

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Contact List Updated June 2013

### For Further Information

Tektronix maintains a comprehensive, constantly expanding collection of application notes, technical briefs and other resources to help engineers working on the cutting edge of technology. Please visit [www.tektronix.com](http://www.tektronix.com)



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